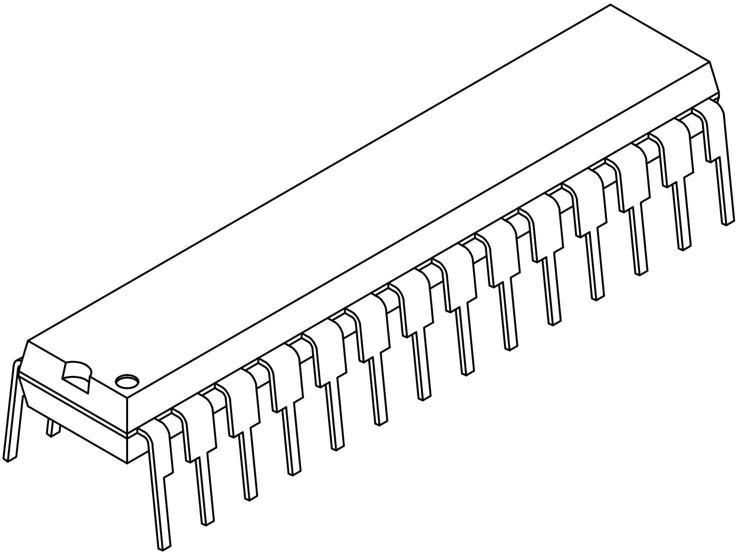
28-Lead Skinny Plastic Dual In-Line (SP) - 300 mil Body [SPDIP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	N	28			28		
Pitch	e	.100 BSC			2.54 BSC		
Top to Seating Plane	A	-	-	.200	-	-	5.08
Molded Package Thickness	A2	.120	.135	.150	3.05	3.43	3.81
Base to Seating Plane	A1	.015	-	-	0.38	-	-
Shoulder to Shoulder Width	E	.290	.310	.335	7.37	7.87	8.51
Molded Package Width	E1	.240	.285	.295	6.10	7.24	7.49
Overall Length	D	1.345	1.365	1.400	34.16	34.67	35.56
Tip to Seating Plane	L	.110	.130	.150	2.79	3.30	3.81
Lead Thickness	c	.008	.010	.015	0.203	0.254	0.381
Upper Lead Width	b1	.045	.050	.070	1.14	1.27	1.78
Lower Lead Width	b	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	-	-	.430	-	-	10.92

Notes:

1. The Pin 1 visual index feature may vary, but it must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. The theoretically exact value is shown without tolerances.